

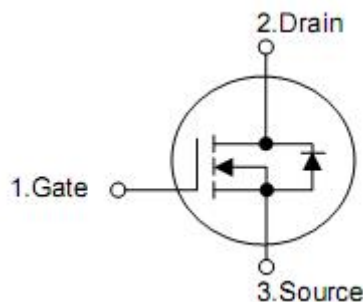
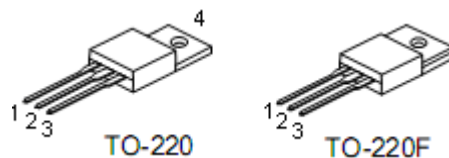
1. Description

The KIA8N60 is a high voltage MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

2. Features

- n $R_{DS(on)}=0.98\Omega$ @ $V_{GS}=10V$
- n Ultra low gate charge (typical 29nC)
- n Fast switching capability
- n Avalanche energy tested
- n Improved dv/dt capability,

3. Pin configuration



Pin	Function
1	Gate
2	Drain
3	Source
4	Drain

4. Absolute maximum ratings

(T_C=25°C , unless otherwise specified)

Parameter	Symbol	Rating		Units	
		TO220	TO220F		
Drain-source voltage	V _{DSS}	600		V	
Gate-source voltage	V _{GSS}	±30		V	
Drain current continuous	I _D	T _C =25°C	7.5	7.5*	A
		T _C =100°C	4.6	4.6*	A
Drain current pulsed (note1)	I _{DP}	30	30*	A	
Peak diode recovery dv/dt (note3)	dv/dt	4.5		V/ns	
Total power dissipation	P _D	T _C =25°C	147	48	W
		Derate above 25°C	1.18	0.38	W/°C
Junction temperature	T _J	+150		°C	
Storage temperature	T _{STG}	-55~+150		°C	

* Drain current limited by maximum junction temperature

5. Thermal data

Parameter	Symbol	Rating		Unit
		TO220	TO220F	
Thermal resistance junction-ambient	R _{thJA}	62.5		°C/W
Thermal resistance, case-to-Sink Typ	R _{thCS}	0.5	--	°C/W
Thermal resistance junction-case	R _{thJC}	0.85	2.6	°C/W

6. Electrical characteristics

($T_J=25^{\circ}\text{C}$, unless otherwise notes)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Off characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	600	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{DS}=600V, V_{GS}=0V$	-	-	1	μA
		$V_{DS}=480V, T_C=125^{\circ}\text{C}$	-	-	10	μA
Gate-body leakage current	Forward	I_{GSS}	-	-	100	nA
	Reverse				-100	nA
Breakdown voltage temperature coefficient	$\Delta BV_{DSS}/\Delta T_J$	$I_D=250\mu A$	-	0.6	-	V/ $^{\circ}\text{C}$
On characteristics						
Gate threshold voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0	-	4.0	V
Static drain-source on-resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=3.75A$ (Note 4)	-	0.98	1.2	Ω
Dynamic characteristics						
Input capacitance	C_{ISS}	$V_{DS}=25V, V_{GS}=0V, f=1\text{MHz}$	-	100	-	pF
Output capacitance	C_{OSS}		-	110	-	pF
Reverse transfer capacitance	C_{RSS}		-	12	-	pF
Switching characteristics						
Turn-on delay time	$t_{D(ON)}$	$V_{DD}=300V, R_G=25\Omega, I_D=7.5A$ (note 4,5)	-	20	-	ns
Rise time	t_R		-	50	-	ns
Turn-off delay time	$t_{D(OFF)}$		-	80	-	ns
Fall time	t_F		-	70	-	ns
Total gate charge	Q_G	$V_{DS}=480V, V_{GS}=10V, I_D=7.5A$ (note 4,5)	-	29	-	nC
Gate-source charge	Q_{GS}		-	4.7	-	nC
Gate-drain charge	Q_{GD}		-	12.5	-	nC
Drain-source diode characteristics						
Drain-source diode forward voltage	V_{SD}	$V_{GS}=0V, I_{SD}=7.5A$	-	-	1.4	V
Continuous drain-source current	I_{SD}		-	-	7.5	A
Pulsed drain-source current	I_{SM}		-	-	30	A
Reverse recovery time	t_{RR}	$I_{SD}=7.5A, di/dt=100A/\mu A$ (note 4)	-	350	-	ns
Reverse recovery charge	Q_{RR}		-	3.3	-	μC

- Note: 1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $L=7.3\text{mH}, I_{AS}=7.5A, V_{DD}=50V, R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$
3. $I_{SD}\leq 7.5A, di/dt\leq 200A/\mu s, V_{DD}\leq BV_{DSS}$, Starting $T_J=25^{\circ}\text{C}$
4. Pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
5. Essentially independent of operating temperature.

7. Typical characteristics

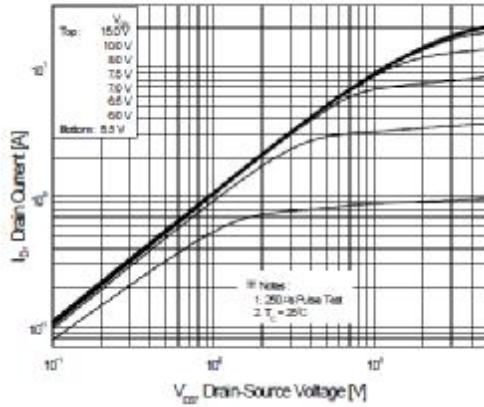


Figure 1. On-Region Characteristics

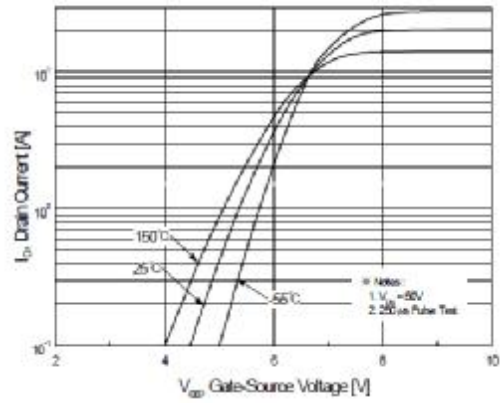


Figure 2. Transfer Characteristics

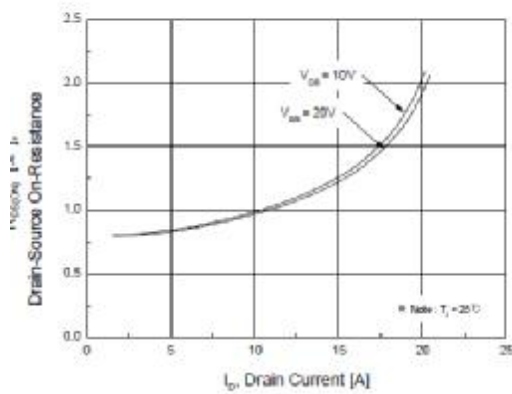


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

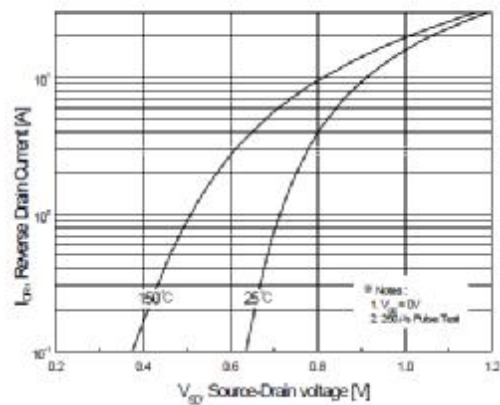


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

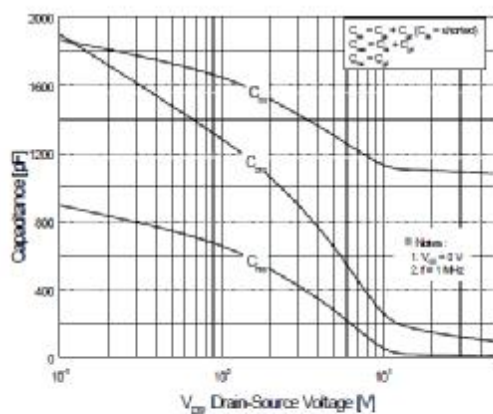


Figure 5. Capacitance Characteristics

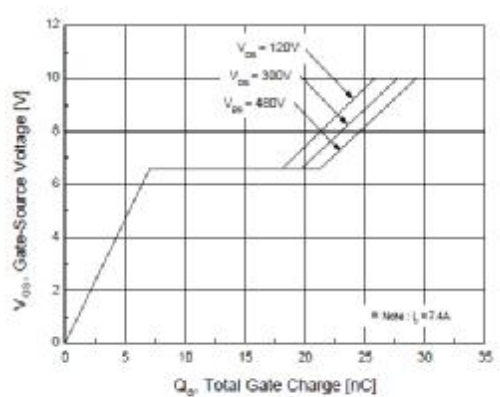


Figure 6. Gate Charge Characteristics

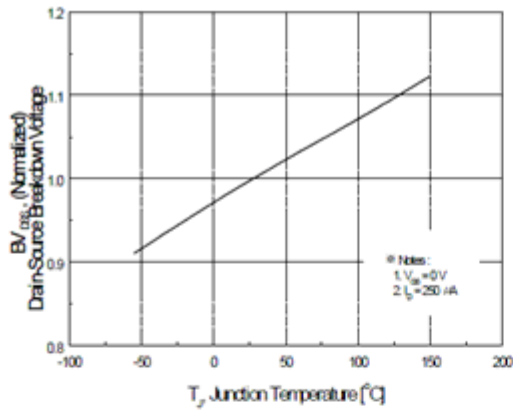


Figure 7. Breakdown Voltage Variation vs. Temperature

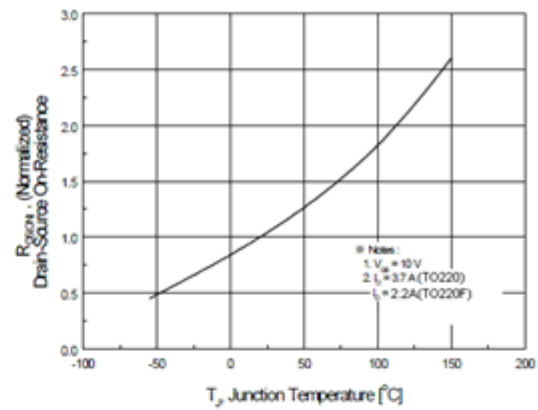


Figure 8. On-Resistance Variation vs. Temperature.

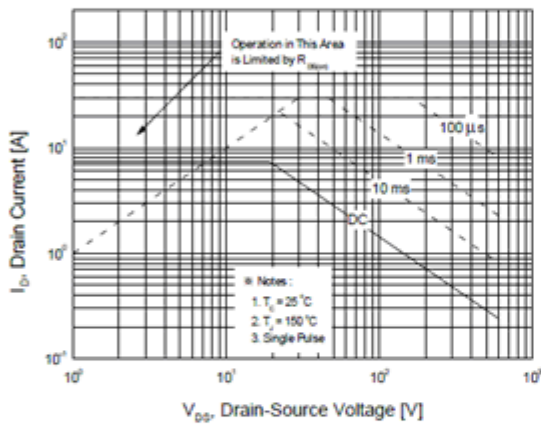


Figure 9. Maximum Safe Operating Area

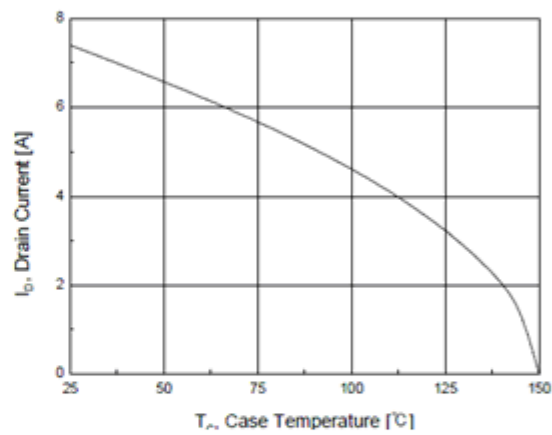


Figure 10. Maximum Drain Current vs Case Temperature

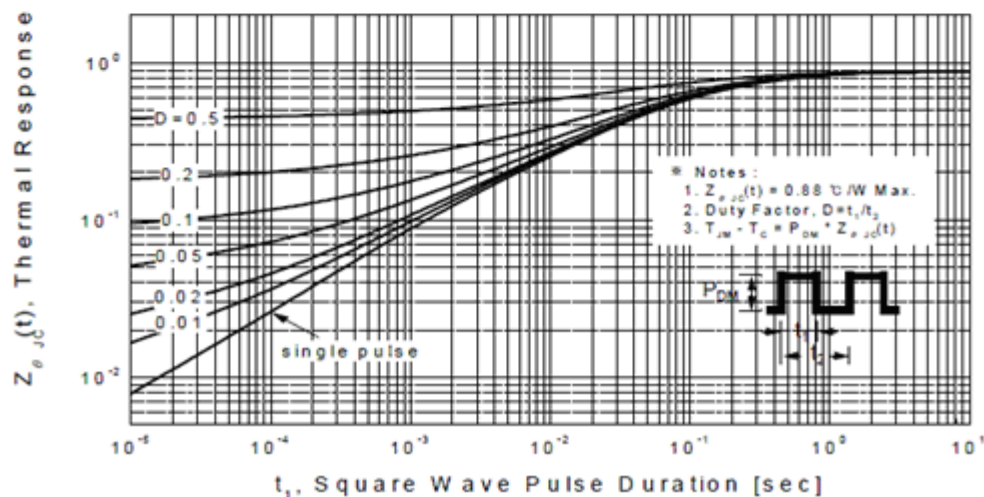


Figure 11-1. Transient Thermal Response Curve for TO220

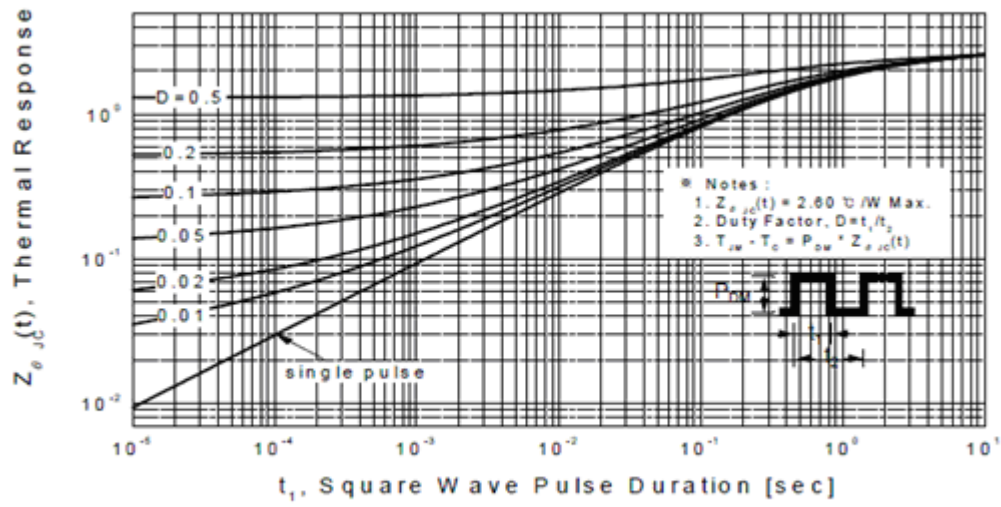


Figure 11-2. Transient Thermal Response Curve for TO220F